

APR 17 1993

Publication of:
Rocha-Alvarez, et al.

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For: PURGE HEATER DESIGN AND
PROCESS DEVELOPMENT FOR
THE IMPROVEMENT OF LOW K
FILM PROPERTIES

BOX NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

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Group Art Unit: 1762

Examiner: Meeks, Timothy

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I hereby certify that this correspondence is being deposited on 4/2, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

4/2/03

Date \_\_\_\_\_

Signature

**RESPONSE TO OFFICE ACTION DATED FEBRUARY 5, 2003**

In response to the Office Action dated February 5, 2003, having a shortened statutory period for response set to expire on May 5, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5269/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

## IN THE SPECIFICATION:

Please replace paragraph [0050] on page 16 with the following paragraph:

**[0050]** In step 630, process gas mixture containing an oxidizer, such as oxygen or ozone (O<sub>3</sub>), and/or a carrier gas, such as argon or helium, and a carbon silicon gas